

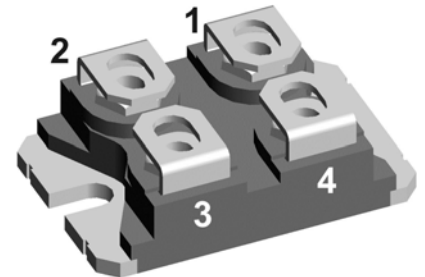
HiPerFRED

$$\begin{aligned} V_{RRM} &= 300\text{ V} \\ I_{FAV} &= 2 \times 30\text{ A} \\ t_{rr} &= 30\text{ ns} \end{aligned}$$

High Performance Fast Recovery Diode
 Low Loss and Soft Recovery
 Parallel legs

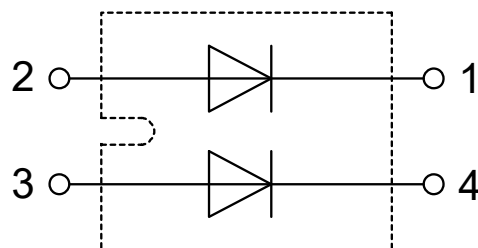
Part number

DSEP2x31-03A



Backside: isolated

 E72873



Features / Advantages:

- Planar passivated chips
- Very low leakage current
- Very short recovery time
- Improved thermal behaviour
- Very low I_{rm} -values
- Very soft recovery behaviour
- Avalanche voltage rated for reliable operation
- Soft reverse recovery for low EMI/RFI
- Low I_{rm} reduces:
 - Power dissipation within the diode
 - Turn-on loss in the commutating switch

Applications:

- Antiparallel diode for high frequency switching devices
- Antisaturation diode
- Snubber diode
- Free wheeling diode
- Rectifiers in switch mode power supplies (SMPS)
- Uninterruptible power supplies (UPS)

Package: SOT-227B (minibloc)

- Isolation Voltage: 3000 V~
- Industry standard outline
- RoHS compliant
- Epoxy meets UL 94V-0
- Base plate: Copper internally DCB isolated
- Advanced power cycling

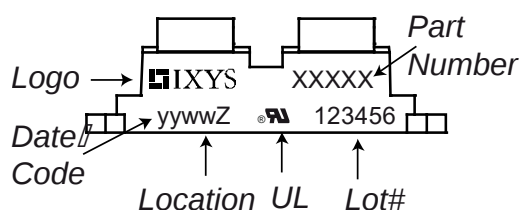
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Fast Diode				Ratings			
Symbol	Definition	Conditions		min.	typ.	max.	Unit
V_{RSM}	max. non-repetitive reverse blocking voltage	$T_{VJ} = 25^{\circ}\text{C}$				300	V
V_{RRM}	max. repetitive reverse blocking voltage	$T_{VJ} = 25^{\circ}\text{C}$				300	V
I_R	reverse current, drain current	$V_R = 300\text{ V}$	$T_{VJ} = 25^{\circ}\text{C}$			10	μA
		$V_R = 300\text{ V}$	$T_{VJ} = 150^{\circ}\text{C}$			1	mA
V_F	forward voltage drop	$I_F = 30\text{ A}$	$T_{VJ} = 25^{\circ}\text{C}$			1,23	V
		$I_F = 60\text{ A}$				1,40	V
		$I_F = 30\text{ A}$	$T_{VJ} = 150^{\circ}\text{C}$			0,90	V
		$I_F = 60\text{ A}$				1,10	V
I_{FAV}	average forward current	$T_C = 105^{\circ}\text{C}$ rectangular $d = 0.5$	$T_{VJ} = 150^{\circ}\text{C}$			30	A
V_{F0}	threshold voltage	} for power loss calculation only		$T_{VJ} = 150^{\circ}\text{C}$		0,71	V
r_F	slope resistance					6,2	m Ω
R_{thJC}	thermal resistance junction to case					1,15	K/W
R_{thCH}	thermal resistance case to heatsink				0,1		K/W
P_{tot}	total power dissipation	$T_C = 25^{\circ}\text{C}$				100	W
I_{FSM}	max. forward surge current	$t = 10\text{ ms}; (50\text{ Hz}), \text{ sine}; V_R = 0\text{ V}$	$T_{VJ} = 45^{\circ}\text{C}$			300	A
C_J	junction capacitance	$V_R = 150\text{ V}$ $f = 1\text{ MHz}$	$T_{VJ} = 25^{\circ}\text{C}$		66		pF
I_{RM}	max. reverse recovery current	$I_F = 30\text{ A}; V_R = 150\text{ V}$ $-di_F/dt = 400\text{ A}/\mu\text{s}$		$T_{VJ} = 25^{\circ}\text{C}$		10	A
				$T_{VJ} = 100^{\circ}\text{C}$		12,5	A
t_{rr}	reverse recovery time			$T_{VJ} = 25^{\circ}\text{C}$		30	ns
				$T_{VJ} = 100^{\circ}\text{C}$		55	ns

Package SOT-227B (minibloc)				Ratings				
Symbol	Definition	Conditions		min.	typ.	max.	Unit	
I _{RMS}	RMS current	per terminal				100	A	
T _{VJ}	virtual junction temperature			-40		150	°C	
T _{op}	operation temperature			-40		125	°C	
T _{stg}	storage temperature			-40		150	°C	
Weight					30		g	
M _D	mounting torque			1,1		1,5	Nm	
M _T	terminal torque			1,1		1,5	Nm	
d _{Spp/App}	creepage distance on surface striking distance through air	terminal to terminal	10,5	3,2			mm	
d _{Spb/Apb}		terminal to backside	8,6	6,8			mm	
V _{ISOL}	isolation voltage	t = 1 second	50/60 Hz, RMS; I _{ISOL} ≤ 1 mA		3000			V
		t = 1 minute			2500			V

Product Marking

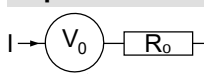


Ordering	Ordering Number	Marking on Product	Delivery Mode	Quantity	Code No.
Standard	DSEP2x31-03A	DSEP2x31-03A	Tube	10	473278

Equivalent Circuits for Simulation

* on die level

$T_{VJ} = 150^{\circ}\text{C}$



Fast Diode

$V_{0\max}$ threshold voltage

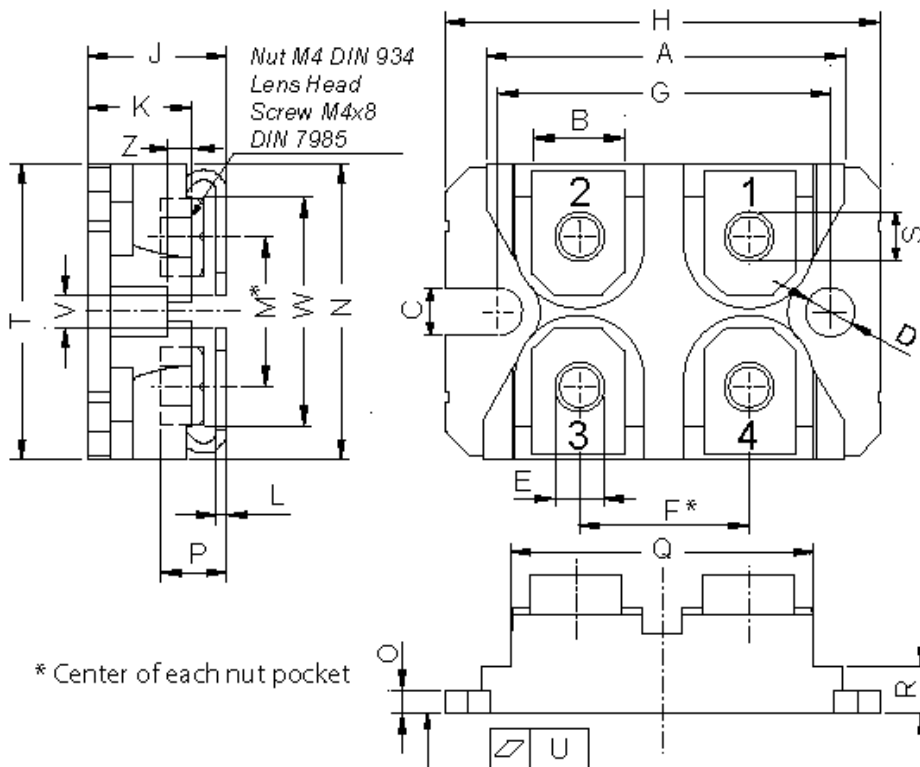
0,71

V

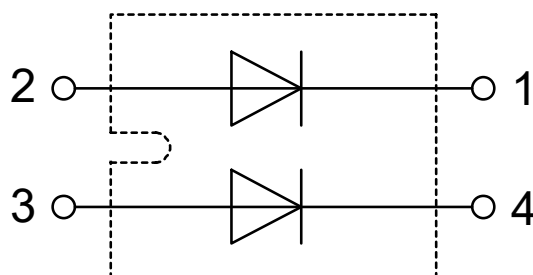
$R_{0\max}$ slope resistance *

4,3

mΩ

Outlines SOT-227B (minibloc)


Dim.	Millimeter		Inches	
	min	max	min	max
A	31.50	31.88	1.240	1.255
B	7.80	8.20	0.307	0.323
C	4.09	4.29	0.161	0.169
D	4.09	4.29	0.161	0.169
E	4.09	4.29	0.161	0.169
F	14.91	15.11	0.587	0.595
G	30.12	30.30	1.186	1.193
H	37.80	38.23	1.488	1.505
J	11.68	12.22	0.460	0.481
K	8.92	9.60	0.351	0.378
L	0.74	0.84	0.029	0.033
M	12.50	13.10	0.492	0.516
N	25.15	25.42	0.990	1.001
O	1.95	2.13	0.077	0.084
P	4.95	6.20	0.195	0.244
Q	26.54	26.90	1.045	1.059
R	3.94	4.42	0.155	0.167
S	4.55	4.85	0.179	0.191
T	24.59	25.25	0.968	0.994
U	-0.05	0.10	-0.002	0.004
V	3.20	5.50	0.126	0.217
W	19.81	21.08	0.780	0.830
Z	2.50	2.70	0.098	0.106



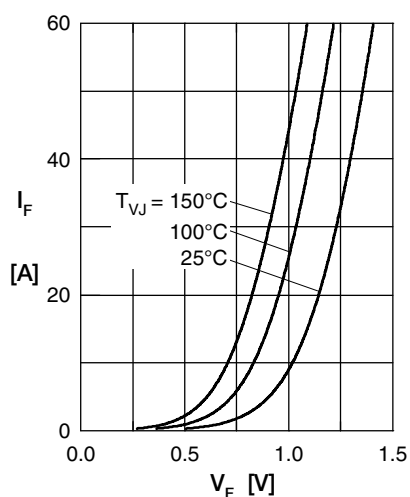
Fast Diode


Fig. 1 Forward current
 I_F versus V_F

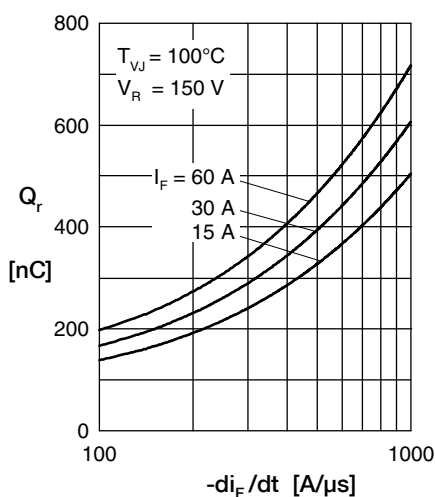


Fig. 2 Typ. reverse recovery charge
 Q_r versus $-di_F/dt$

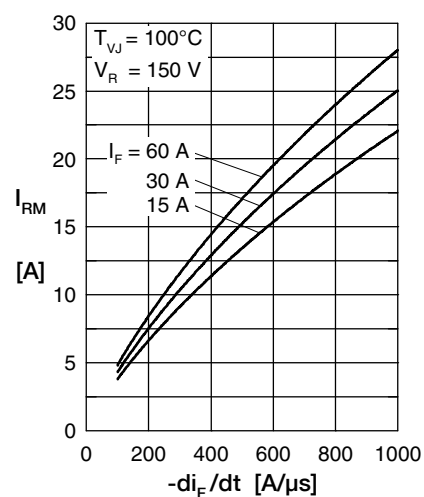


Fig. 3 Typ. peak reverse current
 I_{RM} versus $-di_F/dt$

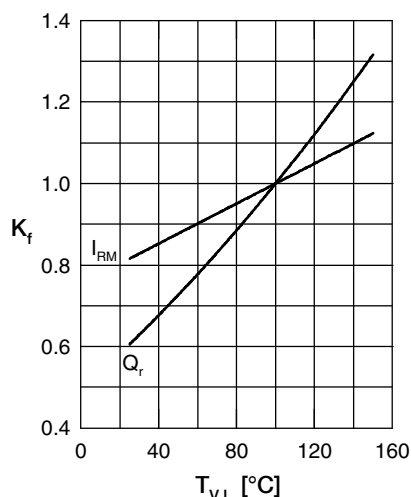


Fig. 4 Typ. dynamic parameters
 Q_r , I_{RM} versus T_{VJ}

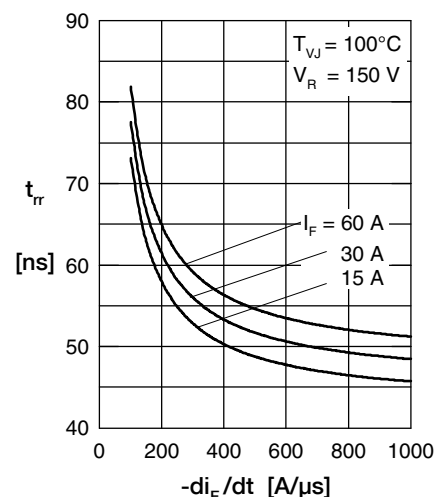


Fig. 5 Typ. recovery time
 t_{rr} versus $-di_F/dt$

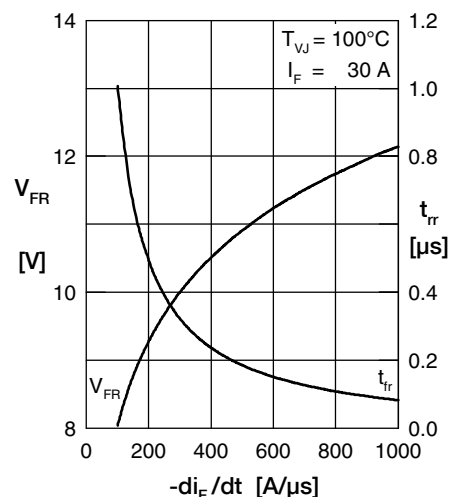


Fig. 6 Typ. peak forward voltage
 V_{FR} and t_{rr} versus di_F/dt

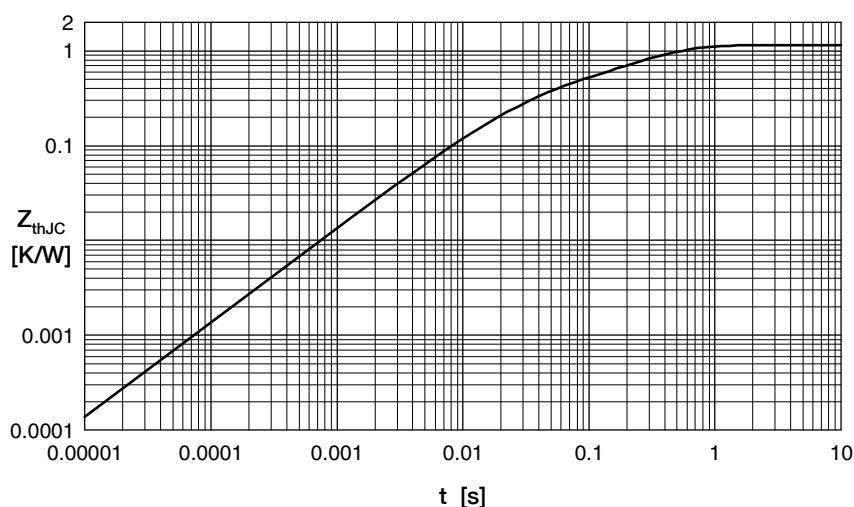


Fig. 7 Transient thermal resistance junction to case

Constants for Z_{thJC} calculation ...A:

i	R_{thi} (K/W)	t_i (s)
1	0.465	0.0052
2	0.179	0.0003
3	0.256	0.0397

Constants for Z_{thJC} calculation ...AR:

i	R_{thi} (K/W)	t_i (s)
1	0.368	0.0052
2	0.1417	0.0003
3	0.0295	0.0004
4	0.5604	0.0092